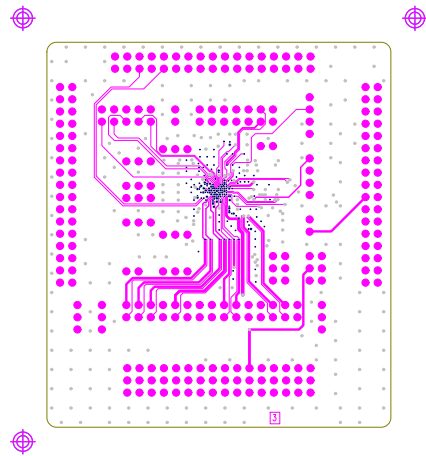
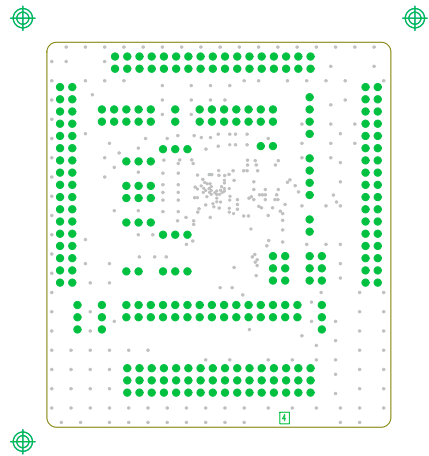


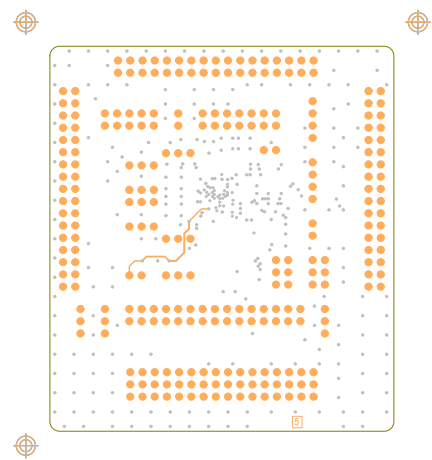
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	DA9066 EVAL. DB
	DRAWING NUMBER 183-05-A C2
LAYER	INNER LAYER 2



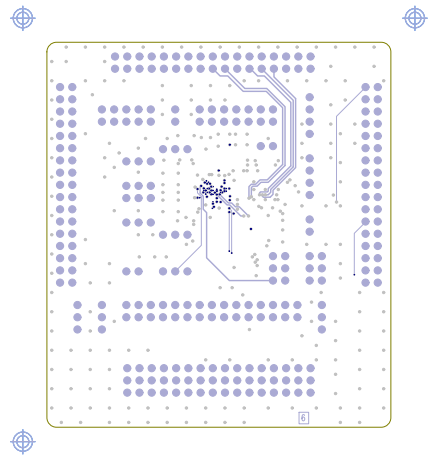
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	DA9066 EVAL. DB
	DRAWING NUMBER 183-05-A C3
LAYER	INNER LAYER 3



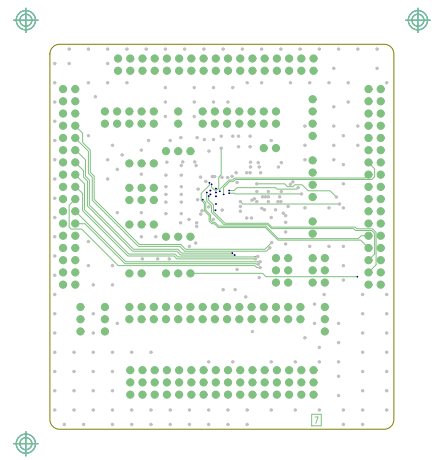
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	DA9066 EVAL. DB
DRAWING NUMBER	183-05-A_C4
LAYER	BOTTOM SIDE TRACK



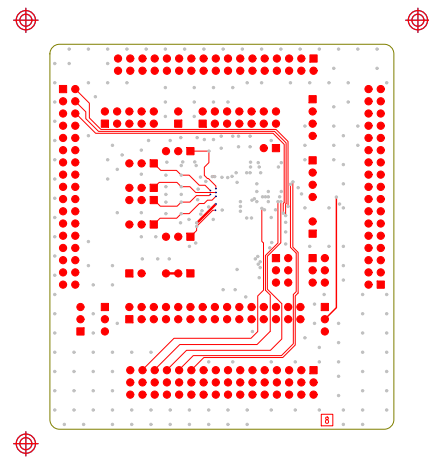
	PROJECT
	DA9066 EVAL. DB
DRAWING NUMBER	183-05-A
LAYER	



	PROJECT
	DA9066 EVAL. DB
DRAWING NUMBER	183-05-A
LAYER	

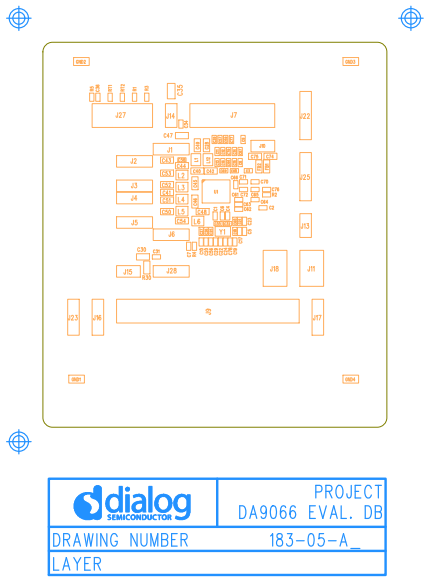


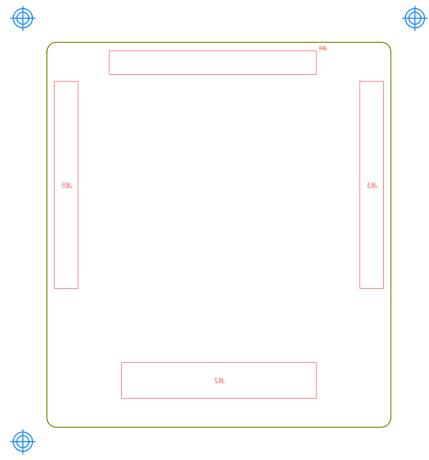
	PROJECT
	DA9066 EVAL. DB
DRAWING NUMBER	183-05-A
LAYER	



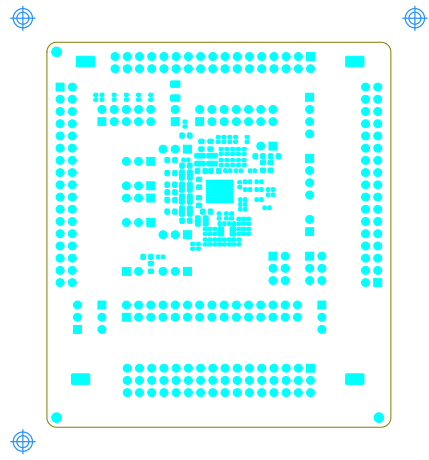
	PROJECT
	DA9066 EVAL. DB
DRAWING NUMBER	183-05-A
LAYER	



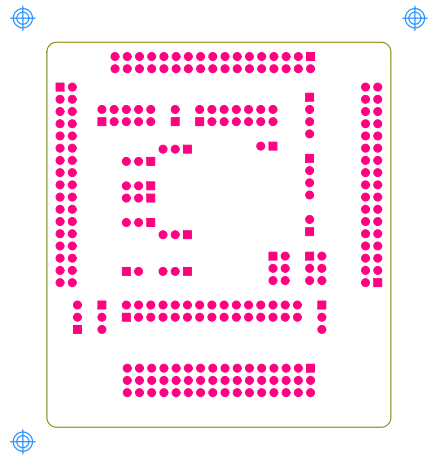




	PROJECT
	DA9066 EVAL. DB
DRAWING NUMBER	183-05-A
LAYER	




	PROJECT
	DA9066 EVAL. DB
	DRAWING NUMBER 183-05-A
LAYER	

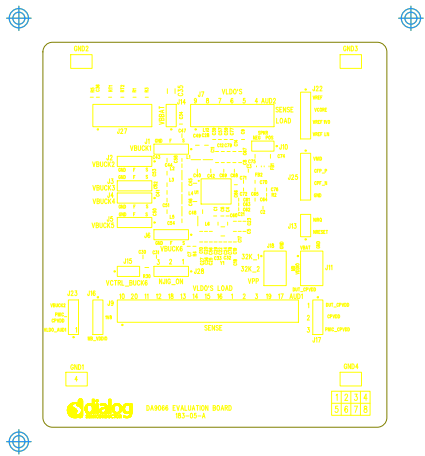


	PROJECT
	DA9066 EVAL. DB
DRAWING NUMBER	183-05-A
LAYER	

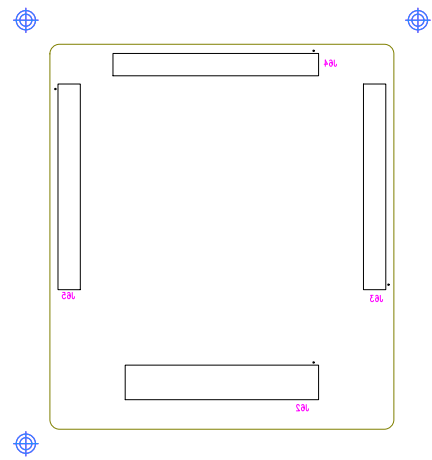


The diagram shows a square microchip layout with a central square core. The core is composed of a grid of small squares, with a denser central area. Surrounding the core are various rectangular blocks and lines, representing different functional blocks and interconnects. The layout is enclosed in a yellow border, and there are four blue registration marks at the corners.

	PROJECT DA9066 EVAL. DB
DRAWING NUMBER	183-05-A
LAYER	

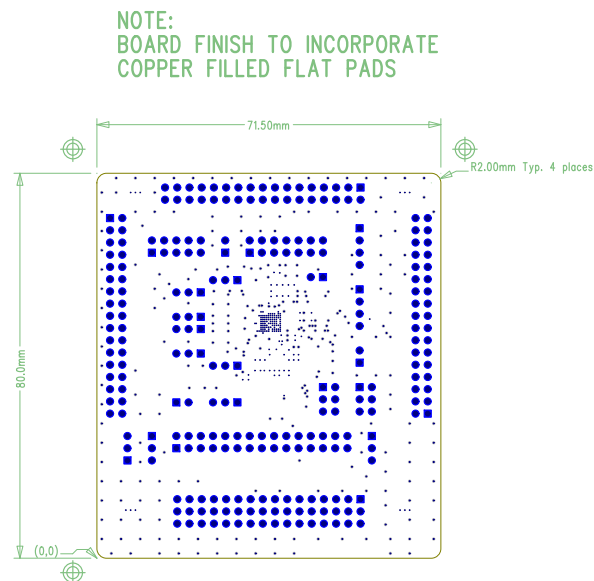


	PROJECT DA9066 EVAL. DB
DRAWING NUMBER	183-05-A TS
LAYER	TOP SILKSCREEN



	PROJECT
	DA9066 EVAL. DB
	DRAWING NUMBER 183-05-A_BS
LAYER	BOTTOM SILKSCREEN

IF IN DOUBT ASK!



MANUFACTURE DETAIL MC



COMPANY CONFIDENTIAL

TOLERANCES UNLESS OTHERWISE STATED  
0 PLACE DECIMALS  $\pm 1$   
1 PLACE DECIMALS  $\pm 0.5$   
2 PLACE DECIMALS  $\pm 0.1$

DRAWN BY IT/RJ	DATE 19/02/2013
CHK'D BY	DATE

DIALOG SEMICONDUCTOR UK LTD  
DELTA 200, WELTON ROAD  
SWINDON, WILTS.  
SN5 7XB

© COPYRIGHT 2013	REV A
TITLE MANUFACTURE DETAIL DA9066 EVALUATION BOARD	DRAWING NUMBER 183-05-A

PREFERRED PANELISATION REQUIREMENTS	
REFER TO THE PANEL DRAWING IF SUPPLIED OTHERWISE USE DETAILS BELOW	
PRINTED CIRCUIT BOARDS THAT REQUIRE PANELISATION	
01	ANY PCB THAT DOES NOT HAVE A 5mm CLEARANCE FROM PCB EDGE TO COPPER/COMPONENTS ALONG THE LONGEST PARALLEL EDGES
02	ANY 'ODD' SHAPE PCB e.g. ROUND
PANEL SIZE, WASTE EDGE (BORDER) AND WEBBING	
01	PREFERRED PANEL SIZE TO BE 300mm X 230mm (MAXIMUM 450mm SQUARE)
02	PANEL BORDER TO BE 10mm ON ALL SIDES, FULLY CROSS HATCHED IN COPPER ON BOTH SIDES
03	BOARD EDGE TO BOARD EDGE INTERNAL WEBBING TO BE 10mm
TOOLING HOLES	
01	ADD 3 TOOLING HOLES 2.5mm $\pm$ 0.05 DIA. TO PANEL BORDER 5mm FROM BORDER EDGE
FIDUCIALS	
01	ADD 3 FIDUCIALS ON BOTH SIDES (1mm DIA./2mm DIA. CLEARANCE) 5mm FROM PANEL EDGE
RATBITES (FOR REFERENCE SEE ROUTING DETAIL BELOW)	
01	ADD RATBITES IN SAFE AREAS AWAY FROM TRACKS, TOOLING HOLES, SM PADS, VIAS, TEST PADS, GROUND PLANES, VITAL SILKSREEN, THROUGH HOLES, OVERHANGING COMPONENTS ETC.
02	USE LOCATIONS SHOWN BY '*' IF PRESENT
03	THERE MUST BE SUFFICIENT RATBITES TO ENSURE PCB STABILITY
04	THE SPACING BETWEEN RATBITES SHOULD BE BETWEEN 40mm TO 50mm
PREFERRED ROUTING / V-SCORING REQUIREMENTS	
ROUTING	REQUIRED
01	USE A 2.40mm (+/-0.1mm) ROUT
V-SCORING	NOT REQUIRED
WHEN V-SCORING IS APPLIED TO THE BOARD AS A METHOD OF REMOVING THE BREAK-OFF STRIPS THE FOLLOWING RULES ARE TO BE APPLIED	
01	SOLDER MASK TO EDGE CLEARANCE = 0.50mm (20thou)
02	COPPER TO EDGE CLEARANCE (ON ALL LAYERS) = 1.00mm (40thou)
03	SCORE ANGLE = 30 deg
04	REMAINING WEB AFTER SCORING IS AS ONE THIRD OF THE PCB NOMINAL THICKNESS

[illegible]

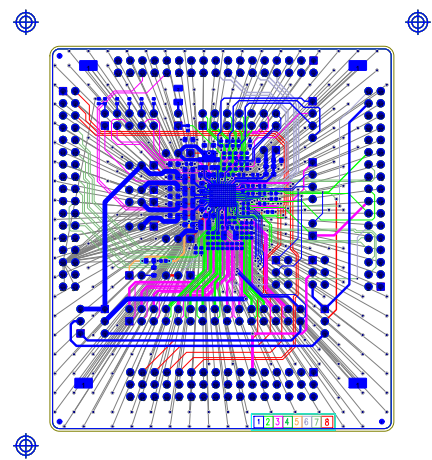
PCB LAYER	MANUFACTURING DETAIL	GERBER FILES
	TOP SILKSCREEN	183-05-A_TS.GER
	TOP RESIST	183-05-A_TR.GER
LAYER 1	TOP SIDE TRACK	183-05-A_C1.GER
LAYER 2	INNER LAYER 2	183-05-A_C2.GER
LAYER 3	INNER LAYER 3	183-05-A_C3.GER
LAYER 4	GROUND LAYER 4	183-05-A_C4.GER
LAYER 5	POWER LAYER 5	183-05-A_C5.GER
LAYER 6	INNER LAYER 6	183-05-A_C6.GER
LAYER 7	INNER LAYER 7	183-05-A_C7.GER
LAYER 8	BOTTOM SIDE TRACK	183-05-A_C8.GER
	BOTTOM RESIST	183-05-A_BR.GER
	BOTTOM SILKSCREEN	183-05-A_BS.GER
	CNC DRILL FILE (LAYERS 1-2)	183-05-A_L1-2.DRT
	CNC DRILL TOOLING (LAYERS 1-2)	183-05-A_L1-2.TOL
	CNC DRILL FILE (LAYERS 2-3)	183-05-A_L2-3.DRT
	CNC DRILL TOOLING (LAYERS 2-3)	183-05-A_L2-3.TOL
	CNC DRILL FILE (LAYERS 6-7)	183-05-A_L6-7.DRT
	CNC DRILL TOOLING (LAYERS 6-7)	183-05-A_L6-7.TOL
	CNC DRILL FILE (LAYERS 7-8)	183-05-A_L7-8.DRT
	CNC DRILL TOOLING (LAYERS 7-8)	183-05-A_L7-8.TOL
	CNC DRILL FILE (LAYERS 3-6)	183-05-A_L3-6.DRT
	CNC DRILL TOOLING (LAYERS 3-6)	183-05-A_L3-6.TOL
	CNC DRILL FILE (PLATED/NON-PLATED THROUGH HOLE)	183-05-A_DRT
	CNC DRILL TOOLING (PLATED/NON-PLATED THRU HOLE)	183-05-A_TOL
	MANUFACTURE DETAIL	183-05-A_MC.GER

LAYER/ LAYER TYPE	BOARD STACK	COPPER WEIGHT
01 MIXED		305g/m
02 MIXED		152g/m
03 MIXED		152g/m
04 GROUND		152g/m
05 POWER		152g/m
06 MIXED		152g/m
07 MIXED		152g/m
08 MIXED		305g/m

### TYP. BOARD CONSTRUCTION

0.012 mm		(1) Cu Foil 12um
0.071 mm		VT-47 Prepreg 1080
0.005 mm		(2) Cu Foil 5um
0.071 mm		VT-47 Prepreg 1080
0.012 mm		(3) Cu Foil 12um
0.098 mm		VT-47 Prepreg 2113
0.156 mm		VT-47 Prepreg 7628
0.121 mm		VT-47 Prepreg 2116
0.186 mm		(4-5) VT-47 0.152mm 17/17
0.121 mm		VT-47 Prepreg 2116
0.186 mm		VT-47 Prepreg 7628
0.098 mm		VT-47 Prepreg 2113
0.012 mm		(6) Cu Foil 12um
0.071 mm		VT-47 Prepreg 1080
0.005 mm		(7) Cu Foil 5um
0.071 mm		VT-47 Prepreg 1080
0.012 mm		(8) Cu Foil 12um





POWER SUPPLY RACK C1